

Oct. 4. 2005 3:59PM

RECEIVED
CENTRAL FAX CENTER

No. 0429 P. 1

Atty. Docket No. CPAC 1017-5
Appl. No. 10/632,552

OCT 04 2005

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Marcos KARNEZOS)

) Examiner: Chris C. CIU

Application No.: 10/632,552)

) Group Art Unit: 2815

Filed: August 2, 2003)

) Date: October 4, 2005

Title: **Semiconductor multi-package module having**)
package stacked over die-up flip chip)
ball grid array package and having wire)
bond interconnect between stacked packages)

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this correspondence is being sent by facsimile to:
Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, at the
Central Fax No. 571 273-8300 on October 4, 2005.

Signed


Bill Keuncdy

MAIL STOP RCF
COMMISSIONER FOR PATENTS
P.O. Box 1450
ALEXANDRIA, VA 22313-1450

AMENDMENT

Dear Sir:

In response to the Office action mailed April 4, 2005, kindly amend the application as follows.

Amendments to the Claims are reflected in the Listing of Claims which begins on page 2 of this paper.

Remarks begin on page 6 of this paper.

- 1 -